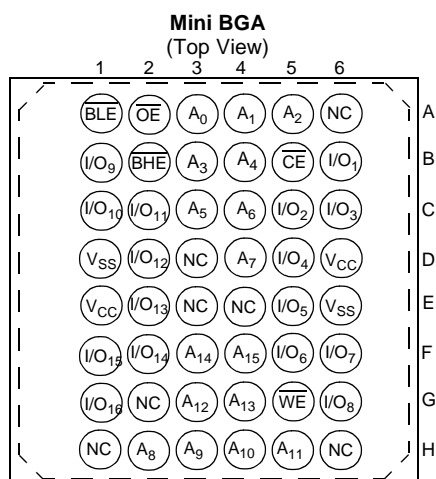


## Pin Configurations



### Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -65°C to +150°C

Ambient Temperature with  
Power Applied..... -55°C to +125°C

Supply Voltage on  $V_{CC}$  to Relative GND<sup>[2]</sup> .... -0.5V to +4.6V

DC Voltage Applied to Outputs  
in High Z State<sup>[2]</sup> ..... -0.5V to  $V_{CC}+0.5V$

DC Input Voltage<sup>[2]</sup> ..... -0.5V to  $V_{CC}+0.5V$

**Note:**

2. Minimum voltage is -2.0V for pulse durations of less than 20 ns.

Current into Outputs (LOW) ..... 20 mA

Static Discharge Voltage..... >2001V  
(per MIL-STD-883, Method 3015)

Latch-Up Current..... >200 mA

### Operating Range

Range	Ambient Temperature	$V_{CC}$
Commercial	0°C to +70°C	3.3V ± 10%
Industrial	-40°C to +85°C	3.3V ± 10%

**Electrical Characteristics** Over the Operating Range

Parameter	Description	Test Conditions		7C1021BV-8		7C1021BV-10		7C1021BV-12		7C1021BV-15		Unit
				Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = −4.0 mA		2.4		2.4		2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA			0.4		0.4		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage			2.2	V <sub>CC</sub> +0.3V	2.2	V <sub>CC</sub> +0.3V	2.2	V <sub>CC</sub> +0.3V	2.2	V <sub>CC</sub> +0.3V	V
V <sub>IL</sub>	Input LOW Voltage <sup>[2]</sup>			−0.3	0.8	−0.3	0.8	−0.3	0.8	−0.3	0.8	V
I <sub>IX</sub>	Input Load Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>		−1	+1	−1	+1	−1	+1	−1	+1	μA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub> , Output Disabled		−1	+1	−1	+1	−1	+1	−1	+1	μA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub> = 1/t <sub>RC</sub>	Com		170		160		150		140	mA
			Ind		190		120		170		160	mA
I <sub>SB1</sub>	Automatic CE Power-Down Current — TTL Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>IH</sub> , V <sub>IN</sub> ≥ V <sub>IH</sub> or V <sub>IN</sub> ≤ V <sub>IL</sub> , f = f <sub>MAX</sub>			40		40		40		40	mA
I <sub>SB2</sub>	Automatic CE Power-Down Current — CMOS Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>CC</sub> − 0.3V, V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.3V, or V <sub>IN</sub> ≤ 0.3V, f = 0			5		5		5		5	mA
			L		500		500		500		500	μA

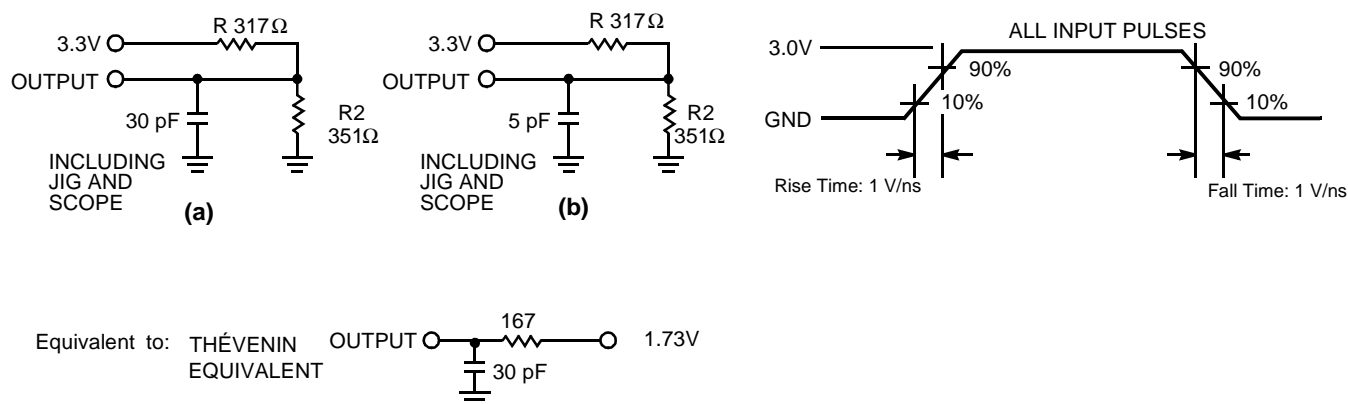
Shaded areas contain advance information.

**Capacitance<sup>[3]</sup>**

Parameter	Description	Test Conditions	Max.	Unit
$C_{IN}$	Input Capacitance	$T_A = 25^\circ\text{C}, f = 1 \text{ MHz}$	6	pF
$C_{OUT}$	Output Capacitance		8	pF

**Note:**

3. Tested initially and after any design or process changes that may affect these parameters.

**AC Test Loads and Waveforms**


**Switching Characteristics<sup>[4]</sup> Over the Operating Range**

Parameter	Description	7C1021BV-8		7C1021BV-10		7C1021BV-12		7C1021BV-15		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE										
t <sub>RC</sub>	Read Cycle Time	8		10		12		15		ns
t <sub>AA</sub>	Address to Data Valid		8		10		12		15	ns
t <sub>OHA</sub>	Data Hold from Address Change	3		3		3		3		ns
t <sub>ACE</sub>	$\overline{CE}$ LOW to Data Valid		8		10		12		15	ns
t <sub>DOE</sub>	$\overline{OE}$ LOW to Data Valid		4		4		6		7	ns
t <sub>LZOE</sub>	$\overline{OE}$ LOW to Low Z	0		0		0		0		ns
t <sub>HZOE</sub>	$\overline{OE}$ HIGH to High Z <sup>[5, 6]</sup>		4		5		6		7	ns
t <sub>LZCE</sub>	$\overline{CE}$ LOW to Low Z <sup>[6]</sup>	3		3		3		3		ns
t <sub>HZCE</sub>	$\overline{CE}$ HIGH to High Z <sup>[5, 6]</sup>		4		5		6		7	ns
t <sub>PU</sub>	$\overline{CE}$ LOW to Power-Up	0		0		0		0		ns
t <sub>PD</sub>	$\overline{CE}$ HIGH to Power-Down		12		12		12		15	ns
t <sub>DBE</sub>	Byte Enable to Data Valid	4			5		6		7	ns
t <sub>LZBE</sub>	Byte Enable to Low Z	0		0		0		0		ns
t <sub>HZBE</sub>	Byte Disable to High Z		4		5		6		7	ns
WRITE CYCLE <sup>[7]</sup>										
t <sub>WC</sub>	Write Cycle Time	8		10		12		15		ns
t <sub>SCE</sub>	$\overline{CE}$ LOW to Write End	7		8		9		10		ns
t <sub>AW</sub>	Address Set-Up to Write End	6		7		8		10		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		0		0		ns
t <sub>PWE</sub>	$\overline{WE}$ Pulse Width	6		8		8		10		ns
t <sub>SD</sub>	Data Set-Up to Write End	4		6		6		8		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		0		0		ns
t <sub>LZWE</sub>	$\overline{WE}$ HIGH to Low Z <sup>[6]</sup>	3		3		3		3		ns
t <sub>HZWE</sub>	$\overline{WE}$ LOW to High Z <sup>[5, 6]</sup>		4		5		6		7	ns
t <sub>BW</sub>	Byte Enable to End of Write	8		8		8		9		ns

Shaded areas contain advance information.

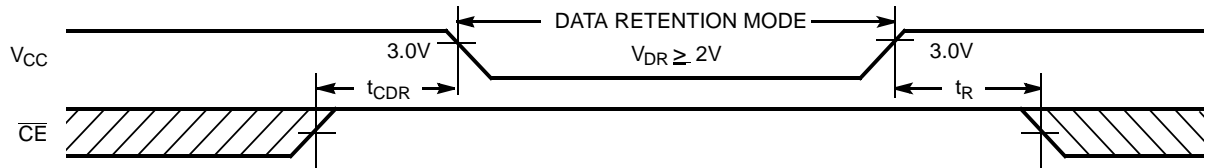
**Data Retention Characteristics Over the Operating Range (L version only)**

Parameter	Description		Conditions <sup>[8]</sup>	Min.	Max.	Unit
$V_{DR}$	$V_{CC}$ for Data Retention			2.0		V
$I_{CCDR}$	Data Retention Current	Com'l	$V_{CC} = V_{DR} = 2.0V$ , $CE \geq V_{CC} - 0.3V$ , $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$		100	$\mu A$
$t_{CDR}^{[9]}$	Chip Deselect to Data Retention Time			0		ns
$t_R^{[10]}$	Operation Recovery Time			$t_{RC}$		ns

**Notes:**

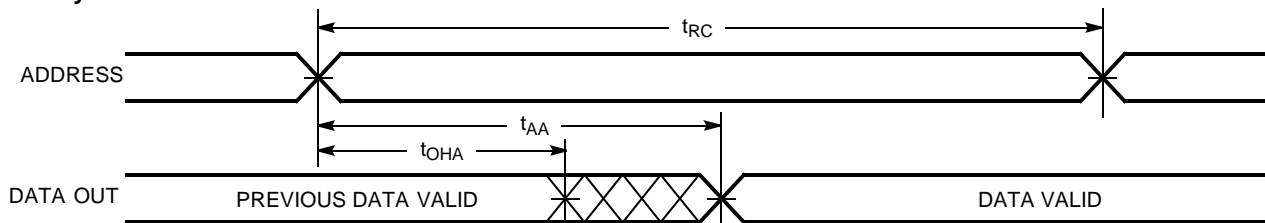
- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $I_{OL}/I_{OH}$  and 30-pF load capacitance.
- $t_{HZOE}$ ,  $t_{HZBE}$ ,  $t_{HZCE}$ , and  $t_{HZWE}$  are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured  $\pm 500$  mV from steady-state voltage.
- At any given temperature and voltage condition,  $t_{HZCE}$  is less than  $t_{LZCE}$ ,  $t_{HZOE}$  is less than  $t_{LZOE}$ , and  $t_{HZWE}$  is less than  $t_{LZWE}$  for any given device.
- The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW,  $\overline{WE}$  LOW and  $\overline{BHE}$  /  $\overline{BLE}$  LOW.  $\overline{CE}$ ,  $\overline{WE}$  and  $\overline{BHE}$  /  $\overline{BLE}$  must be LOW to initiate a write, and the transition of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
- No input may exceed  $V_{CC} + 0.5V$ .
- Tested initially and after any design or process changes that may affect these parameters.
- $t_r \leq 3$  ns for the -12 and -15 speeds.  $t_r \leq 5$  ns for the -20 and slower speeds.

## Data Retention Waveform

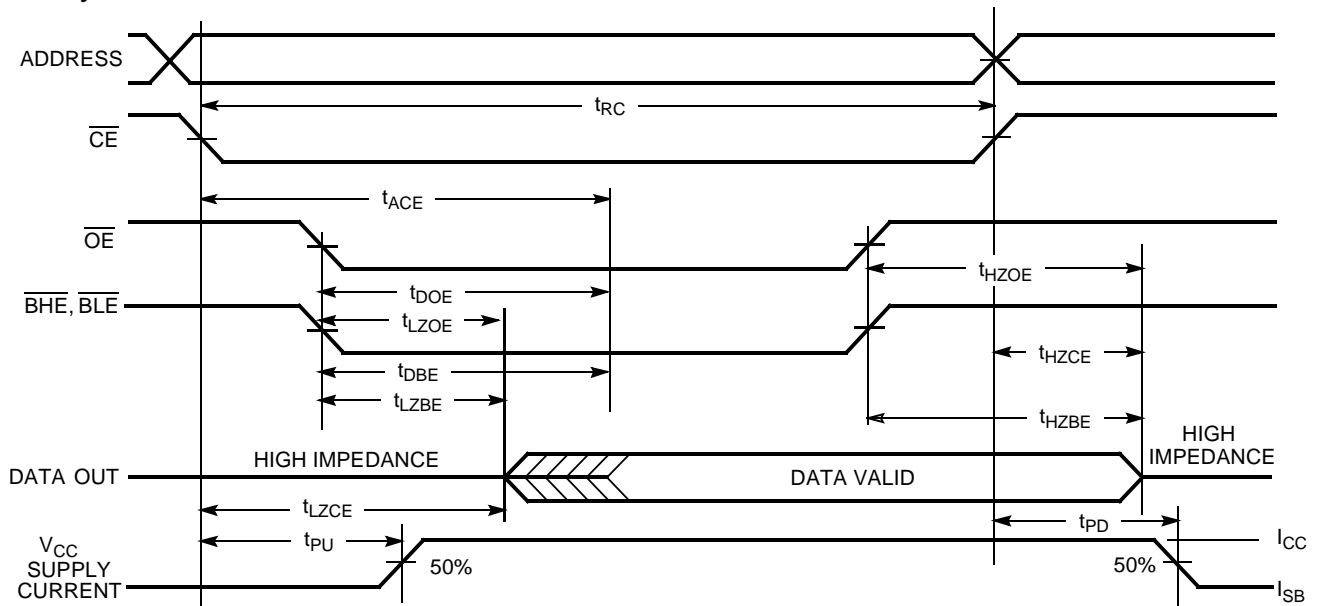


## Switching Waveforms

### Read Cycle No. 1<sup>[11, 12]</sup>

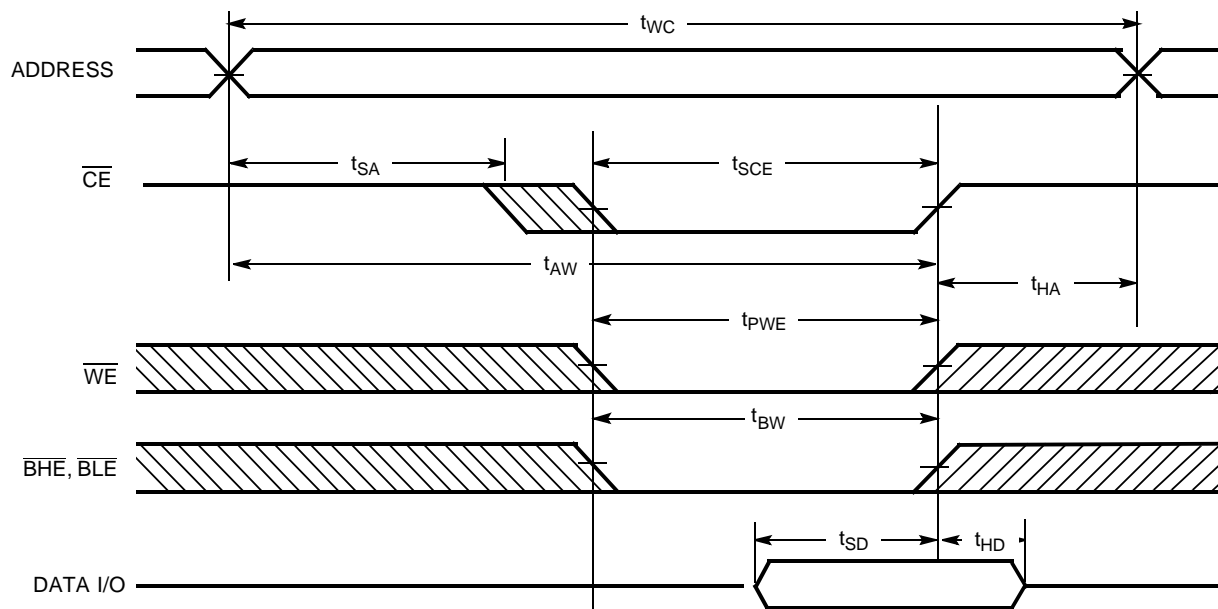
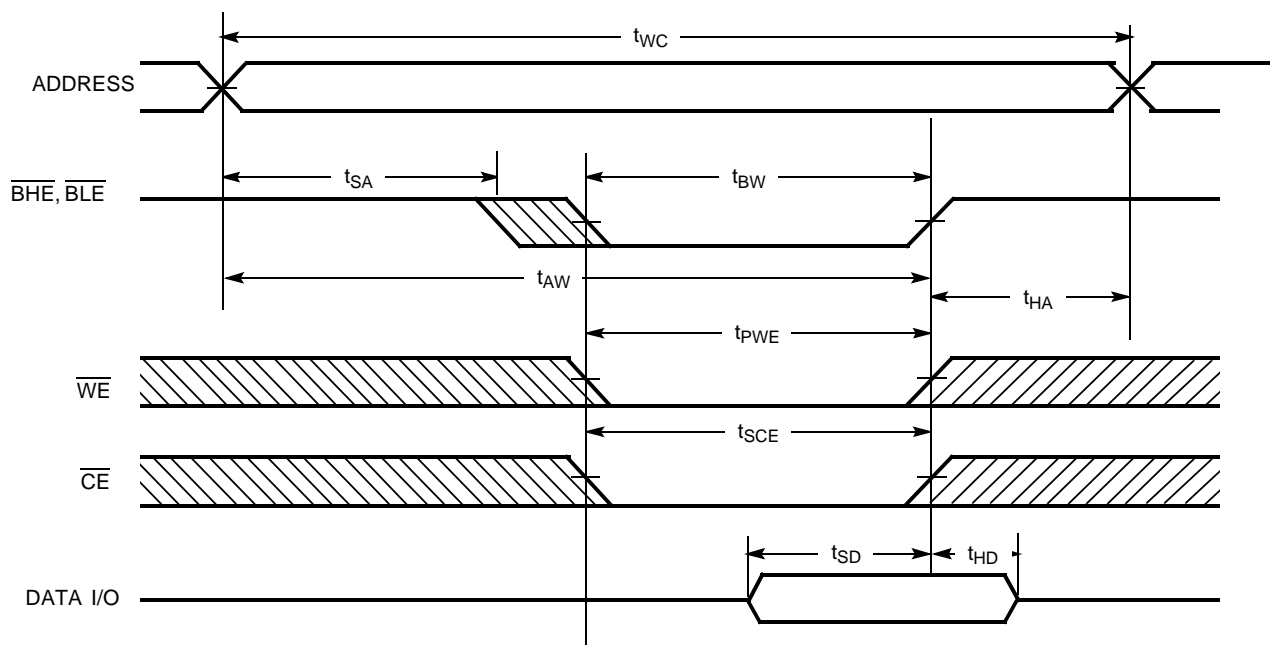


### Read Cycle No. 2 (OE Controlled)<sup>[12, 13]</sup>



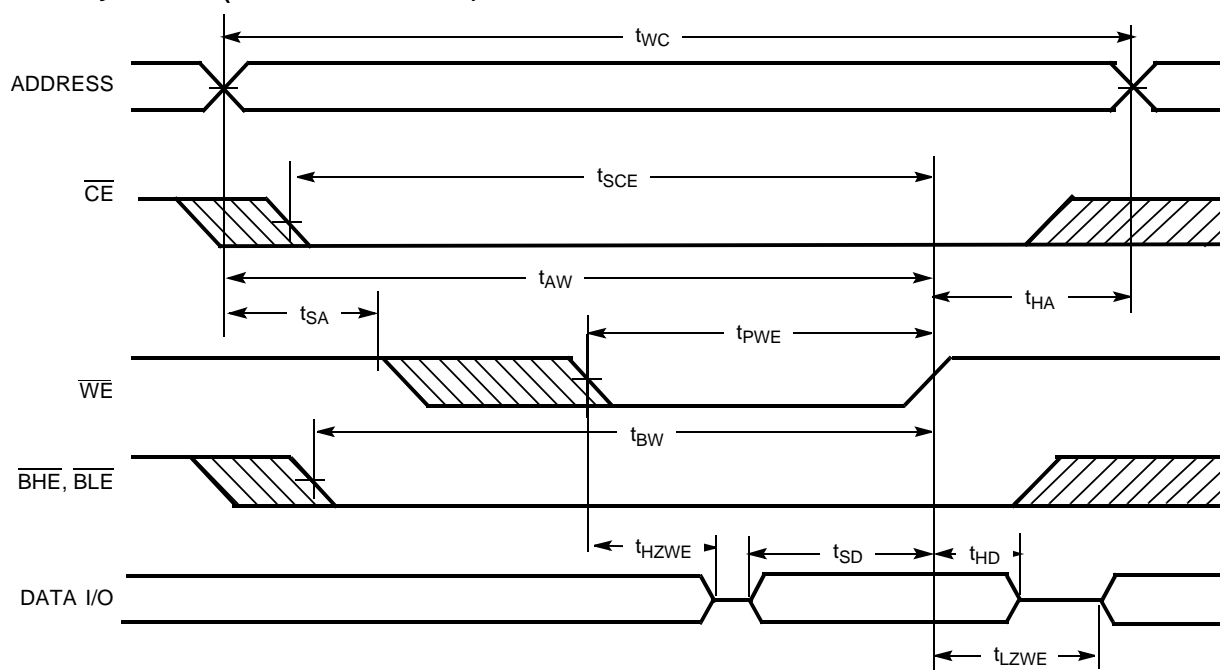
#### Notes:

11. Device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$ ,  $\overline{BHE}$  and/or  $\overline{BLE}$  =  $V_{IL}$ .
12.  $\overline{WE}$  is HIGH for read cycle.
13. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

**Switching Waveforms (continued)**
**Write Cycle No. 1 ( $\overline{\text{CE}}$  Controlled)** <sup>[14, 15]</sup>

**Write Cycle No. 2 ( $\overline{\text{BLE}}$  or  $\overline{\text{BHE}}$  Controlled)**

**Notes:**

14. Data I/O is high impedance if  $\overline{\text{OE}}$  or  $\overline{\text{BHE}}$  and/or  $\overline{\text{BLE}} = V_{\text{IH}}$ .
15. If  $\overline{\text{CE}}$  goes HIGH simultaneously with  $\overline{\text{WE}}$  going HIGH, the output remains in a high-impedance state.

**Switching Waveforms** (continued)

**Write Cycle No. 3 ( $\overline{WE}$  Controlled, LOW)**

**Truth Table**

CE	OE	WE	BLE	BHE	I/O <sub>1</sub> –I/O <sub>8</sub>	I/O <sub>9</sub> –I/O <sub>16</sub>	Mode	Power
H	X	X	X	X	High Z	High Z	Power-Down	Standby ( $I_{SB}$ )
L	L	H	L	L	Data Out	Data Out	Read - All bits	Active ( $I_{CC}$ )
			L	H	Data Out	High Z	Read - Lower bits only	Active ( $I_{CC}$ )
			H	L	High Z	Data Out	Read - Upper bits only	Active ( $I_{CC}$ )
L	X	L	L	L	Data In	Data In	Write - All bits	Active ( $I_{CC}$ )
			L	H	Data In	High Z	Write - Lower bits only	Active ( $I_{CC}$ )
			H	L	High Z	Data In	Write - Upper bits only	Active ( $I_{CC}$ )
L	H	H	X	X	High Z	High Z	Selected, Outputs Disabled	Active ( $I_{CC}$ )
L	X	X	H	H	High Z	High Z	Selected, Outputs Disabled	Active ( $I_{CC}$ )

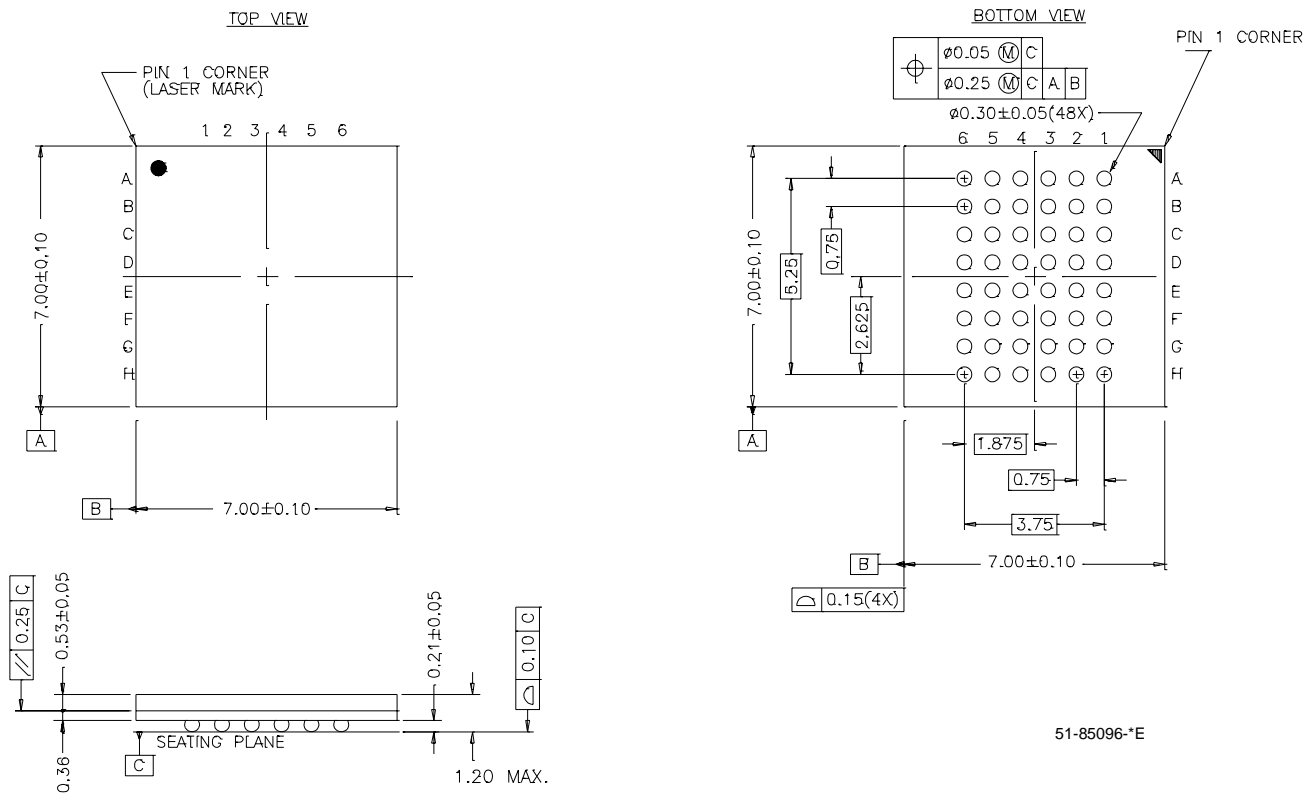
**Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
8	CY7C1021BV33-8BAC	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Commercial
	CY7C1021BV33-8VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33L-8VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33-8ZC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33L-8ZC	Z44	44-Lead TSOP Type II	
10	CY7C1021BV33-10BAC	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Commercial
	CY7C1021BV33-10VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33L-10VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33-10ZC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33L-10ZC	Z44	44-Lead TSOP Type II	
12	CY7C1021BV33-12BAC	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Commercial
	CY7C1021BV33-12VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33L-12VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33-12ZC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33L-12ZC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33-12BAI	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Industrial
	CY7C1021BV33-12VI	V34	44-Lead (400-Mil) Molded SOJ	
15	CY7C1021BV33-15BAC	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Commercial
	CY7C1021BV33L-15BAC	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	
	CY7C1021BV33-15VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33L-15VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33-15ZC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33L-15VC	Z44	44-Lead TSOP Type II	
	CY7C1021BV33-15BAI	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	Industrial
	CY7C1021BV33L-15BAI	BA48A	48-Ball Mini Ball Grid Array (7.00 mm x 7.00 mm)	
	CY7C1021BV33-15VI	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1021BV33L-15ZI	Z44	44-Lead TSOP Type II	

Shaded areas contain advance information.

## Package Diagrams

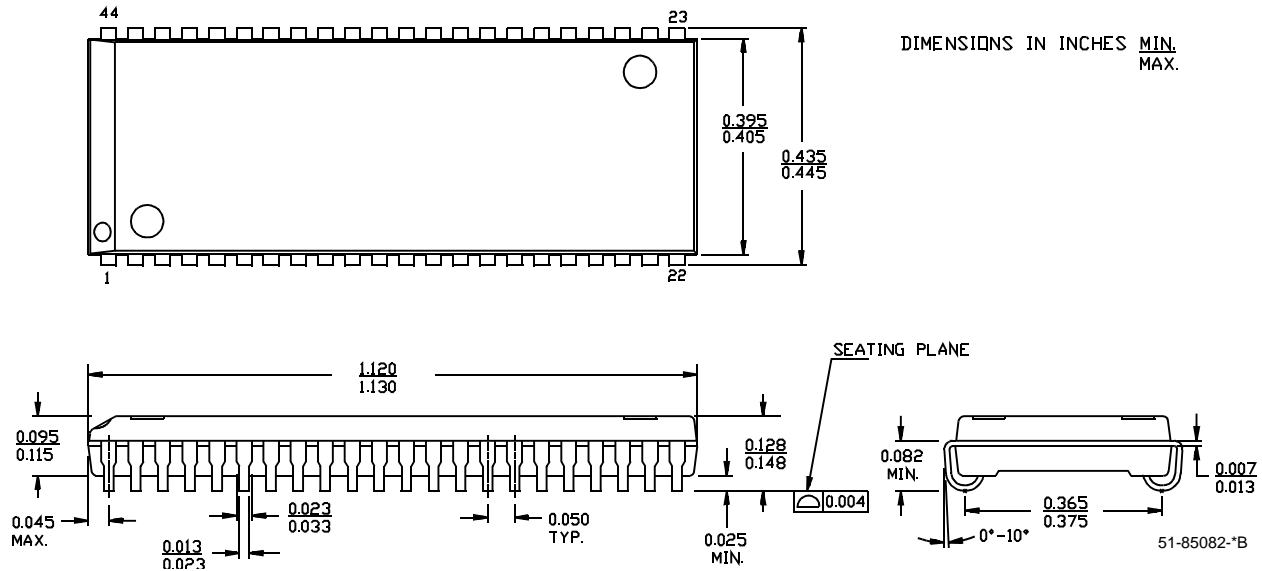
### 48-Ball (7.00 mm x 7.00 mm x 1.2 mm) FBGA BA48A





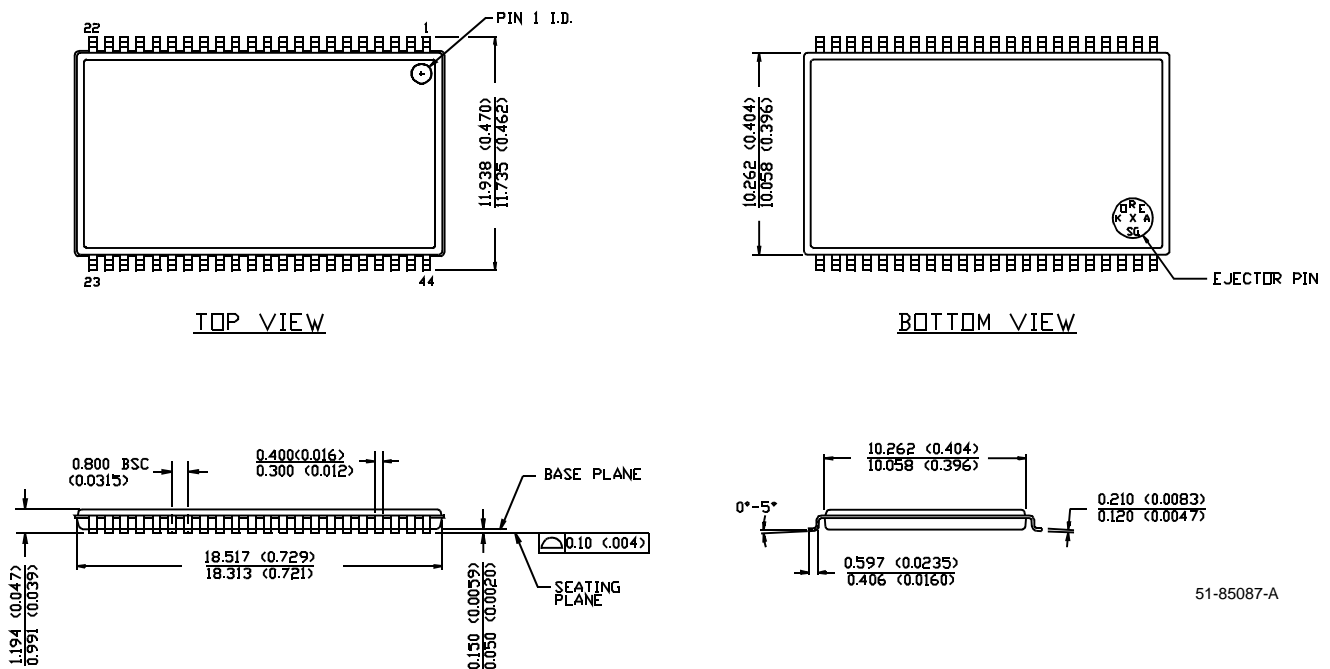
Package Diagrams (continued)

44-Lead (400-Mil) Molded SOJ V34



44-Pin TSOP II Z44

DIMENSION IN MM (INCH)  
MAX.  
MIN.



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## Document History Page

Document Title: CY7C1021BV33 64K x 16 Static RAM Document Number: 38-05148				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	109892	09/22/01	SZV	Change from Spec number: 38-00954 to 38-05148
*A	116474	09/16/02	CEA	Add applications foot note to data sheet, page 1.